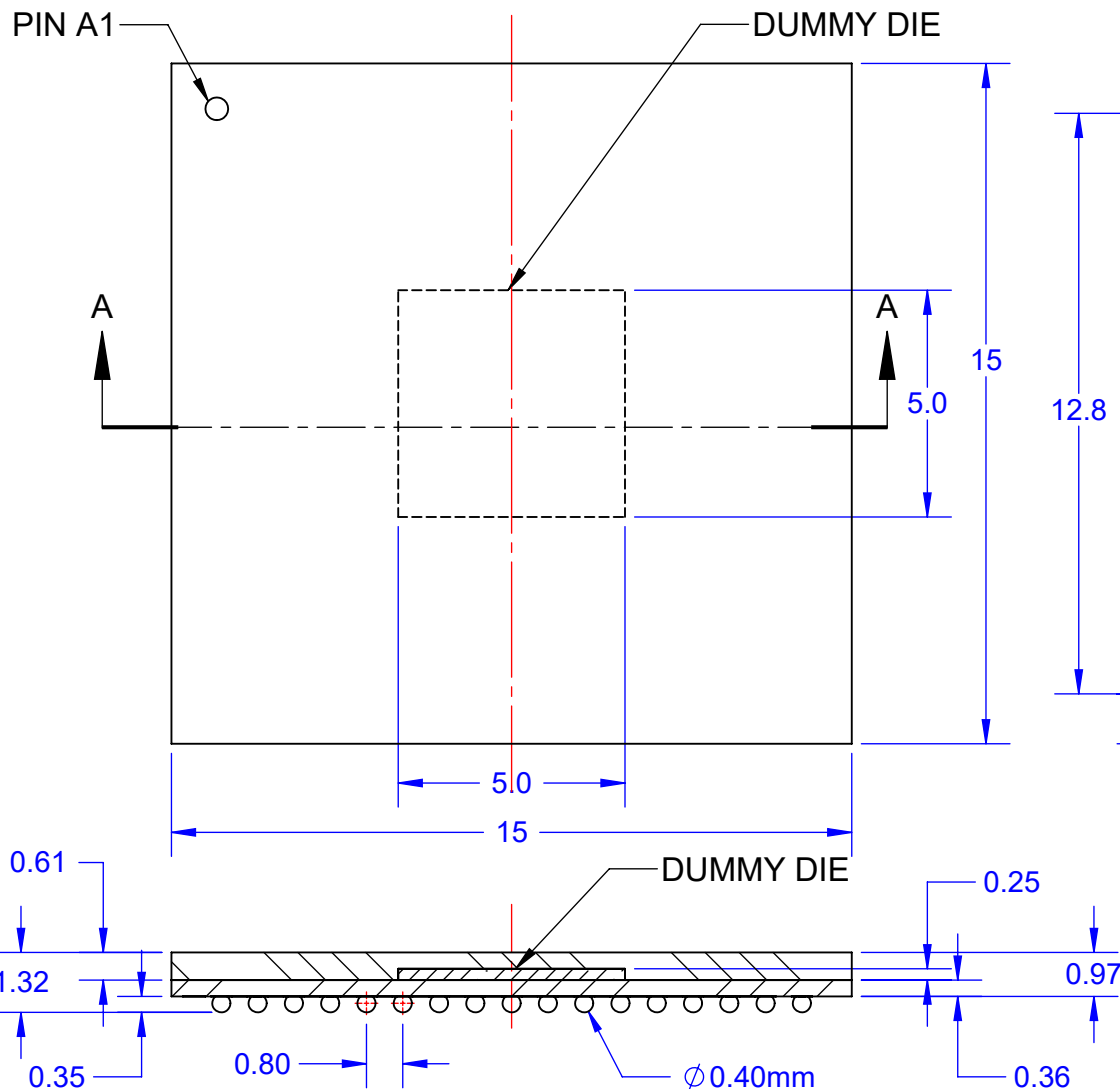
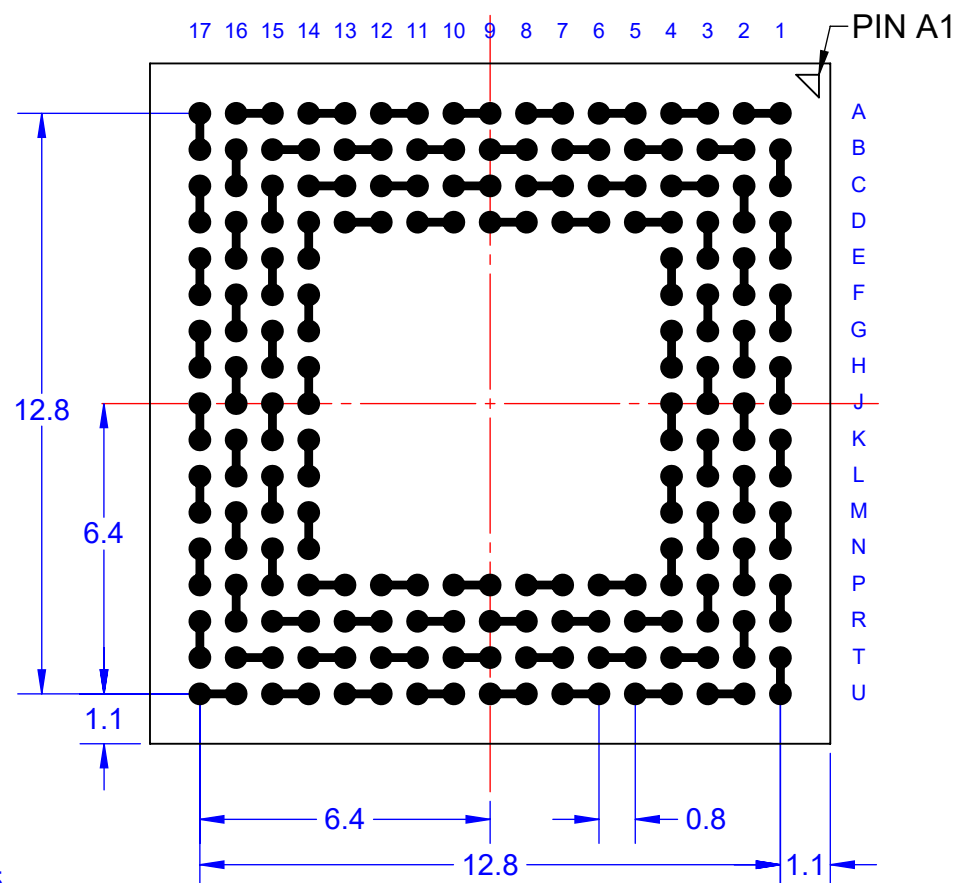


TOP VIEW



SECTION A-A

BALL VIEW



Notes: (Unless Otherwise Specified).

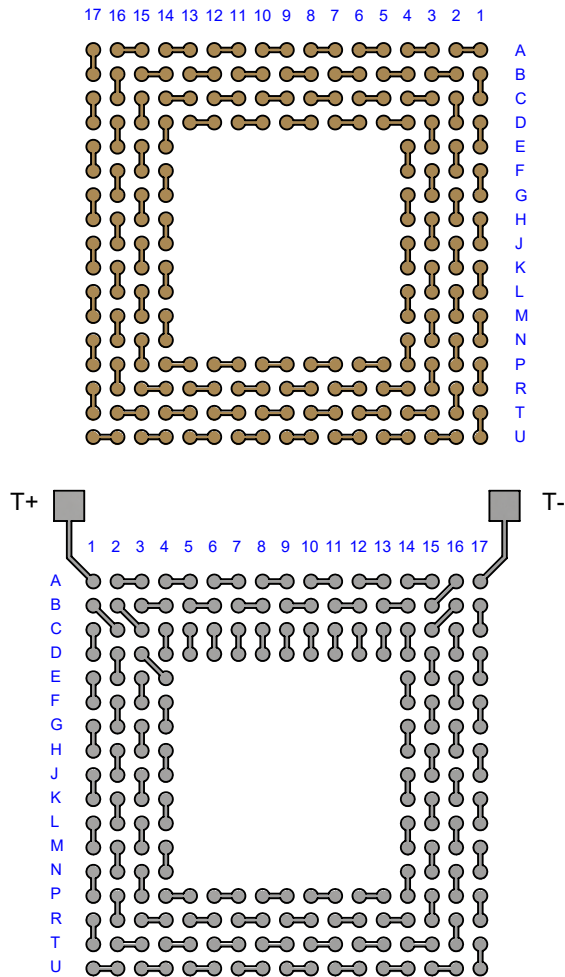
- 1) ALL DIMENSIONS: mm.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm (16 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.37mm (14.5 MIL).
- 5) PAD Cu DIAMETER: 0.46mm (18 MIL).
- 6) SUBSTRATE MATERIAL: BT RESIN.
- 7) DUMMY DIE OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA208T.8C-DC170D	Sn96.5/Ag3.0/Cu0.5	SAC35	YES	YES
BGA208T.8-DC170D	Sn63/Pb37	Sn63	NO	YES

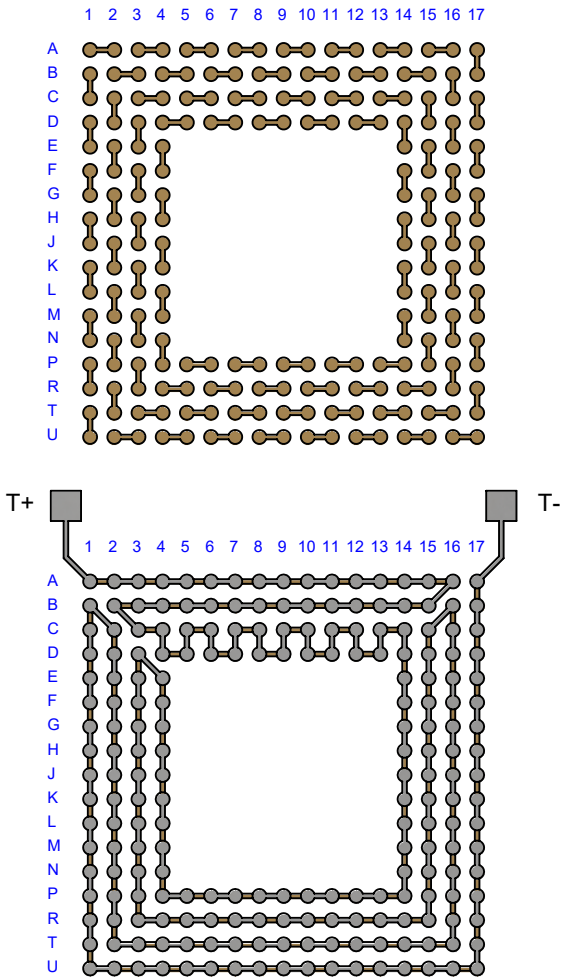
APPROVALS	DATE				
DRAWN T. Au	07/06/25				
ENG M. Hart	07/06/25	TITLE BGA208T.8-DC170D DAISY CHAIN DUMMY			
MFG					
QA		SCALE 6:1	SIZE A	DRAWING NO. 581701	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			
					SHEET 1 OF 4

BALL VIEW



TEST VEHICLE BOARD

BOTTOM SIDE (TOP X-RAY VIEW)

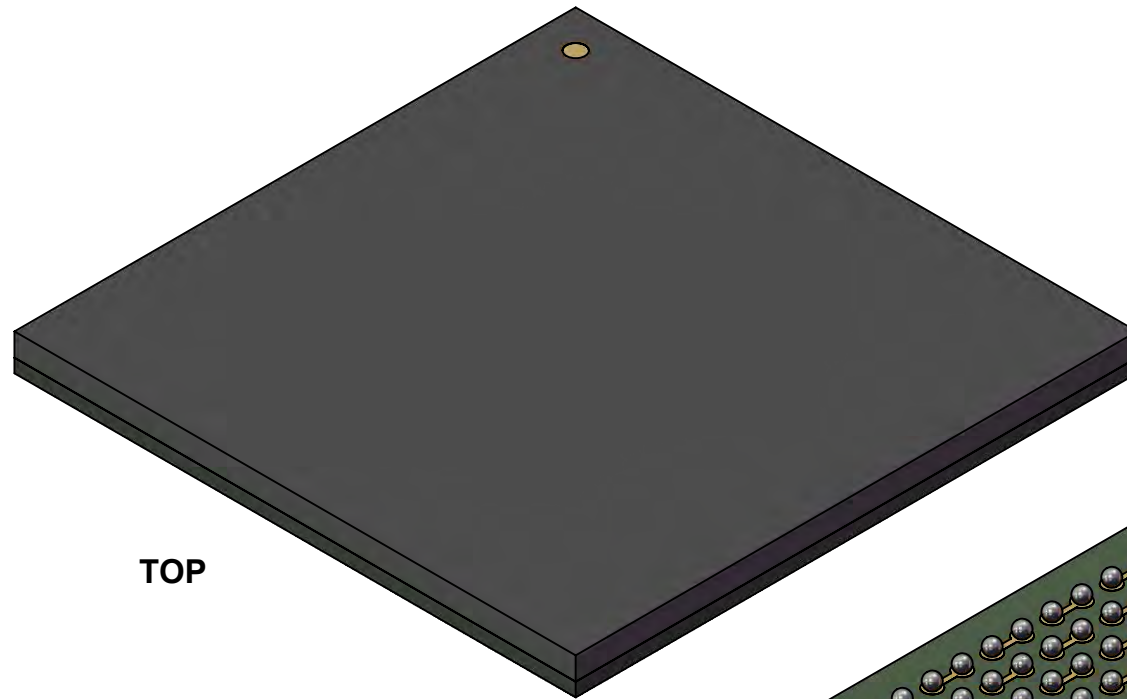


AFTER MOUNTING

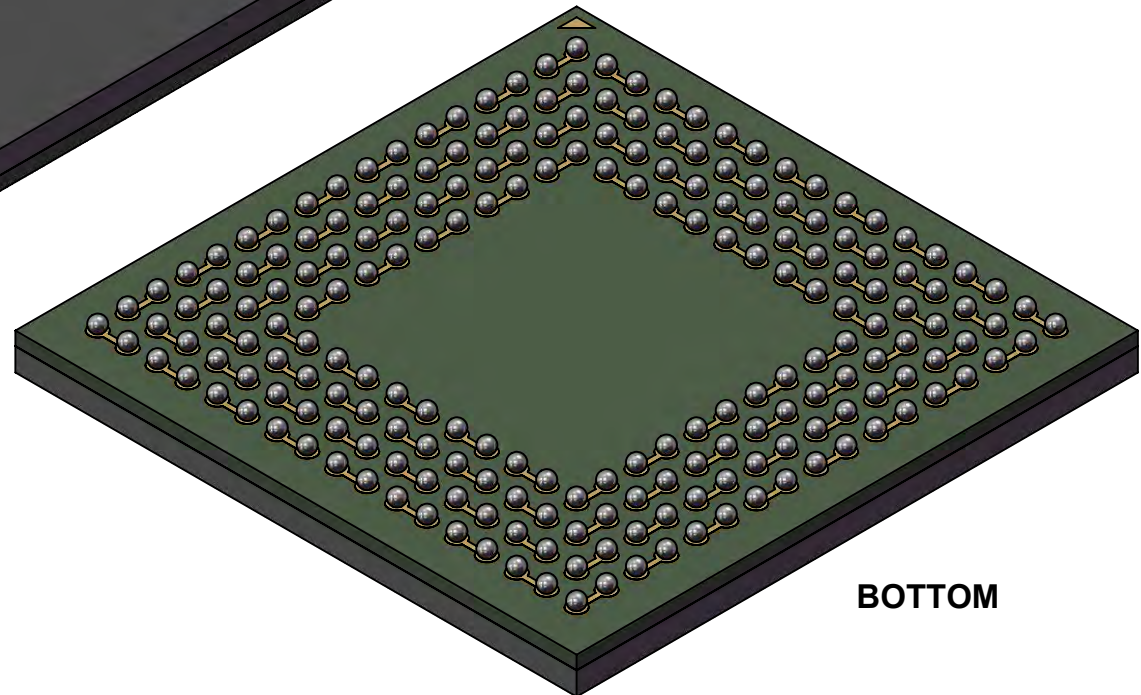
- Notes:
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
 - 2) PCB Cu BALL PAD DIAMETER: 0.46mm (18 MIL).
 - 3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.152mm (6 MIL).
 - 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.37mm (14.5 MIL).

TopLine®			
TITLE BGA208T.8-DC170D DAISY CHAIN DUMMY			
SCALE 4:1	SIZE A	DRAWING NO. 581701	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 4

MODEL



TOP



BOTTOM

TopLine[®]

TITLE BGA208T.8-DC170D
DAISY CHAIN DUMMY

SCALE 7:1	SIZE A	DRAWING NO. 581701	REV A
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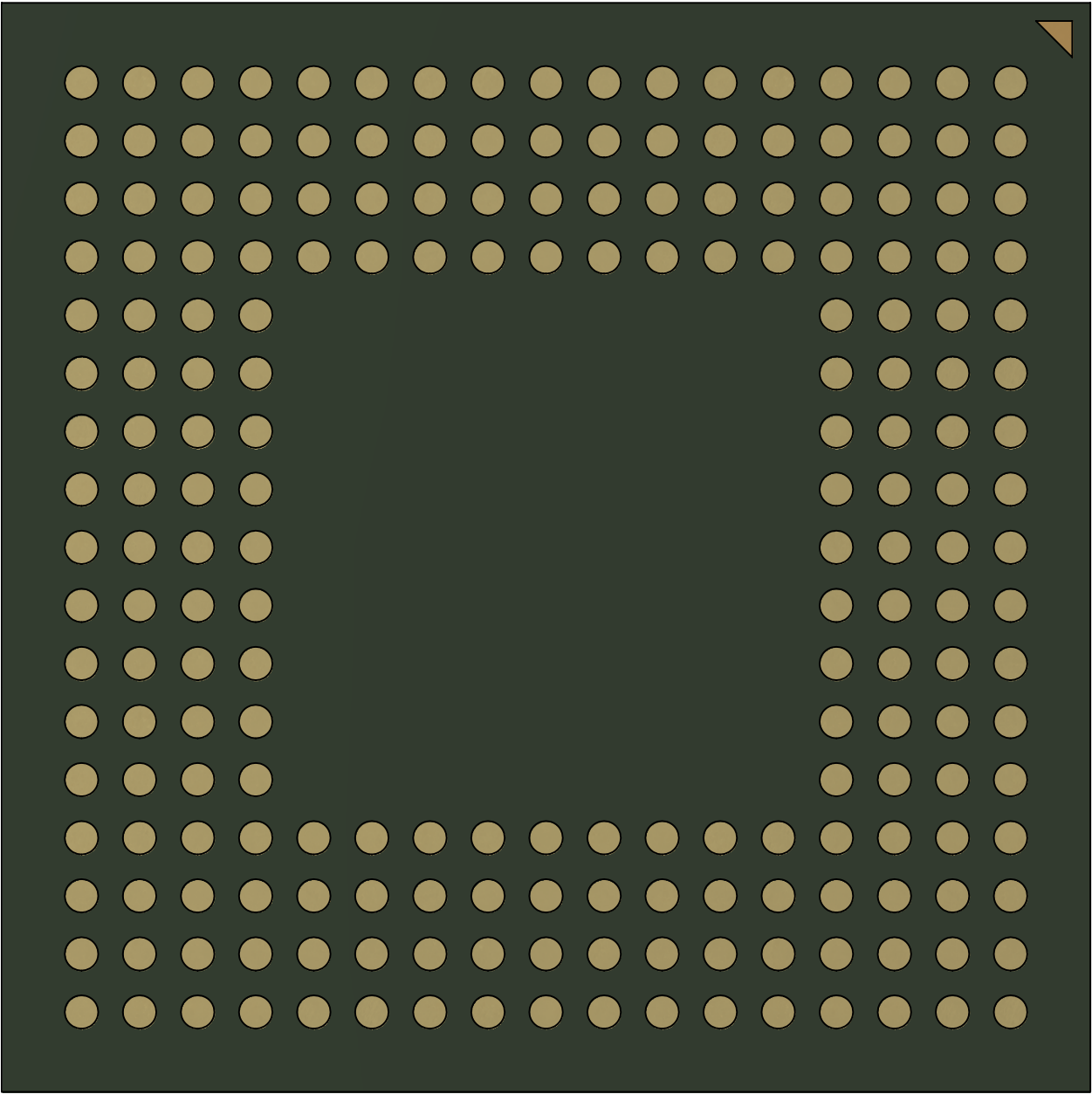
DO NOT SCALE DRAWING

SHEET 3 OF 4

**BOTTOM SOLDER MASK
(RIGHT READING)**

17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1

A
B
C
D
E
F
G
H
J
K
L
M
N
P
R
T
U



TopLine®			
TITLE		BGA208T.8-DC170D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
11:1	A	581701	A
DO NOT SCALE DRAWING			SHEET 4 OF 4